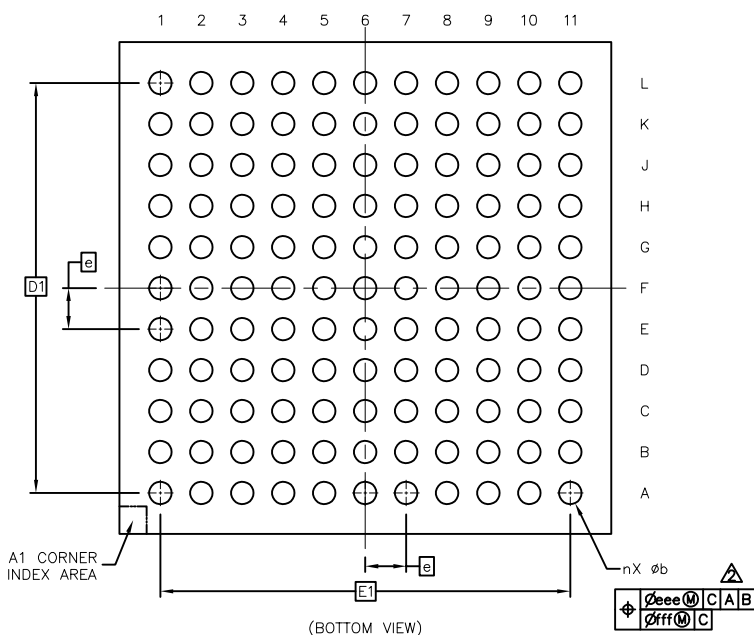
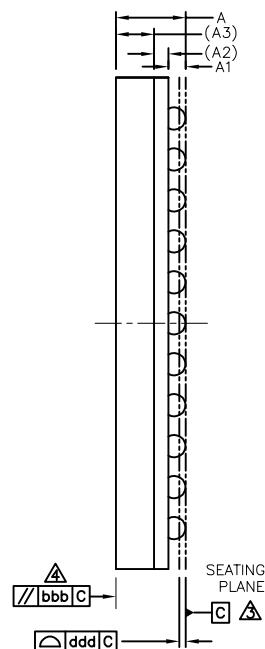
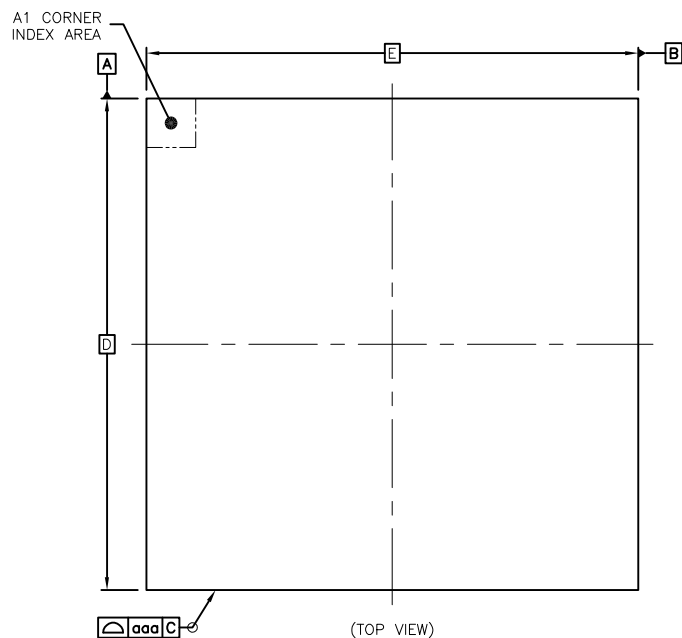




	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOR.	MAX.
TOTAL THICKNESS	A	---	---	1.4
STAND OFF	A1	0.27	---	0.37
SUBSTRATE THICKNESS	A2	0.26		REF
MOLD THICKNESS	A3	0.7		REF
BODY SIZE	D	9		BSC
	E	9		BSC
BALL DIAMETER		0.4		
BALL OPENING		0.3		
BALL WIDTH	b	0.37	---	0.47
BALL PITCH	e	0.75		BSC
BALL COUNT	n	121		
EDGE BALL CENTER TO CENTER	D1	7.5		BSC
	E1	7.5		BSC
BODY CENTER TO CONTACT BALL	SD	---		BSC
	SE	---		BSC
PACKAGE EDGE TOLERANCE	aaa	0.1		
MOLD FLATNESS	bbb	0.2		
COPLANARITY	ddd	0.12		
BALL OFFSET (PACKAGE)	eee	0.15		
BALL OFFSET (BALL)	fff	0.08		

NOTES

- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE C.
- DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE E₆ ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
- ALL DIMENSIONS APPLY TO PbFREE (+) PARTS.
- PACKAGE CODES: X12199M+1C



TITLE:
PACKAGE OUTLINE, 121B, CSBGA-CU
HYBRID, 9X9X1.4mm

APPROVAL	DOCUMENT CONTROL NO. 21-100597	REV. A	1/1
----------	-----------------------------------	-----------	-----

-DRAWING NOT TO SCALE-